

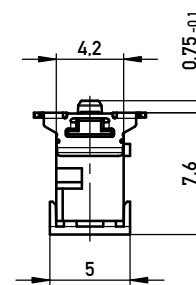
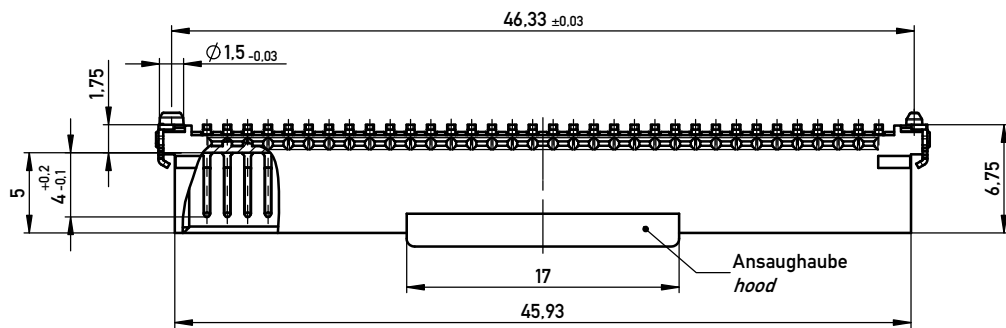
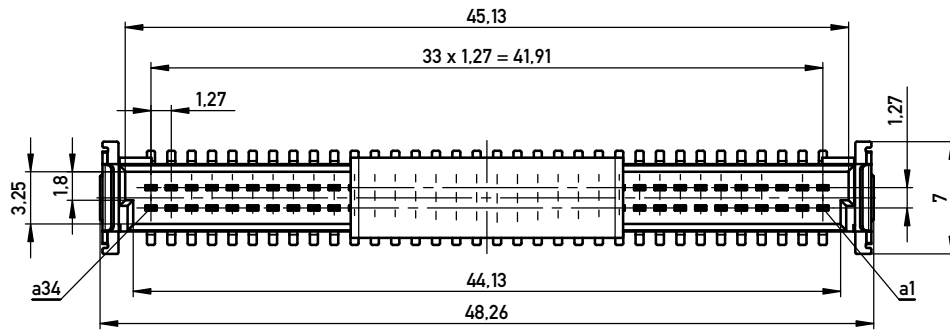
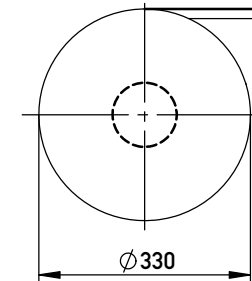
Anforderungsstufe 1  
Performance Level 1

Kontaktbereich vergoldet  
Mating Area gold plating

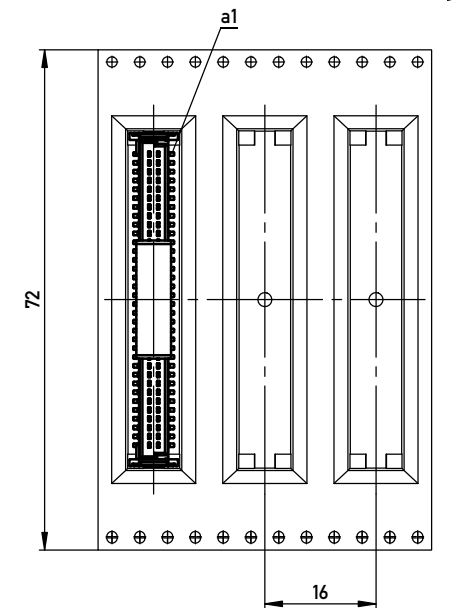
Anschlussbereich verzinkt 4-6 µm  
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0,1 mm  
Coplanarity Area of Termination ≤ 0,1 mm

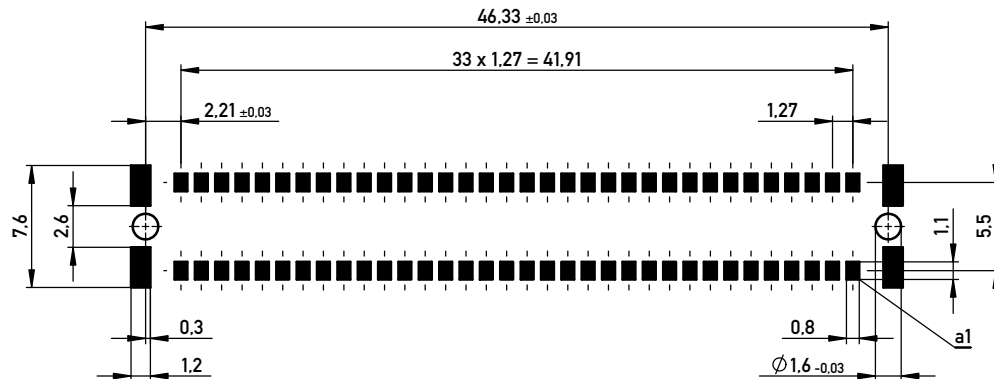
Verpackt im Gurt nach DIN IEC 60286-3  
Tape on Reel Packaging according to DIN IEC 60286-3  
Verpackungseinheit: 280 Stück  
Packaging unit: 280 pcs



Abspulrichtung - Reel off Direction



Leiterplatten-Layout Vorschlag für SMT  
PCB-Layout Proposal for SMT



BA 8-13 - 8mm Bauhöhe  
type 8-13 - Low Profile

|  |  |  |       |                |
|--|--|--|-------|----------------|
| Information:   | Tolerances   | <br>All Dimensions in mm   | Scale | 3:1            |
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| Subject to modification without prior notice. Drawing will not be updated. |  | Designation<br><b>Messertl. SMC-Q 68-SMD-BA8-13</b><br><i>Male SMC-Q 68-SMD-type8-13</i> |       |                |
| www.ERNI.com   |  | <b>244839</b>  |       | I<br><b>A3</b> |
| e  | 30.06.2015   | Class  |       | SMCQ           |
| Index  | Date   |  |       |                |

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